

Solder paste for storage at room temperature

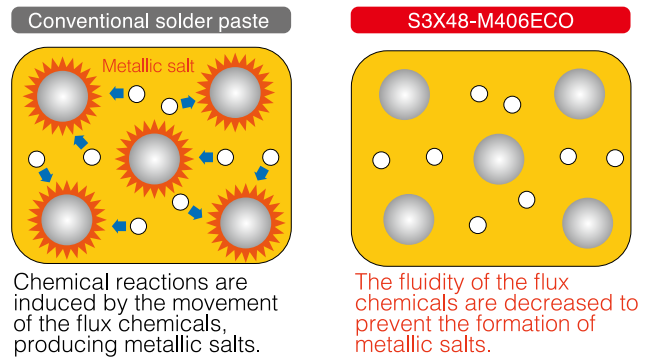
S3X48-M406ECO Sn 3.0Ag 0.5Cu

Has 6 months shelf life at room temperature storage by controlling the formation of metallic salts

Achieves room temperature storage by inhibiting the chemical reaction

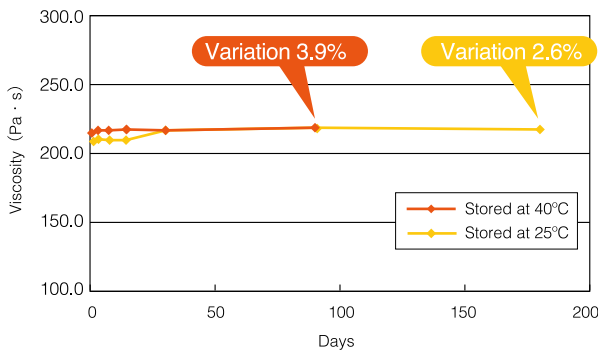
S3X48-M406ECO achieves a long shelf life at room temperature by controlling the occurrence of the chemical reactions. These reactions are controlled within the flux medium and thus the formation of metallic salts are reduced to very minimal levels.

Figure 1. Behavior of flux chemicals in storage



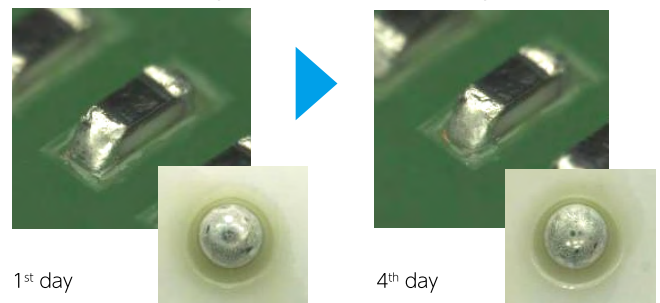
Robust enough to maintain qualities even in a high temperature environment

Viscosity variation after storage at 40°C for 6 months



Solderability in continual use from the previous day (After storage at 40°C for 6 months)

- 1st day: Print 500g of the solder paste for 8 hrs
- 2nd – 4th day: Dispose 250g of the solder paste and add 250g of the fresh solder paste



Benefits of room temperature storage

Being able to store at room temperature brings various significant benefits to cost reduction and increase of production yield. These include such factors as preventing quality degradation in continual use, availability for immediate use without recovering solder paste to room temperature, eliminating the need for overseas refrigerated transport and so on.

Product specifications

Product name	S3X48-M406ECO
Alloy composition (%)	Sn 3.0Ag 0.5Cu
Melting point (°C)	217-219
Particle size (µm)	20-45
Viscosity (Pa.s)	210
Flux content (%)	11.5
Halide content (%)	0
Flux type	ROL0
Shelf life (0~30°C)	6 months
Optional powder size	20 – 38µm Product name: S3X58-M406ECO

- Room temperature storage
- Anti-pillow defect
- Continuous use from previous day
- Fine pitch printing >0.4mm pitch >0.3mm dia. CSP
- Applicable for high pre-heating reflow
- Tack time >36hours
- No clean type